

FDG328P

P-Channel 2.5V Specified PowerTrench® MOSFET

General Description

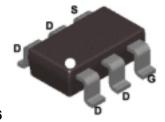
This P-Channel 2.5V specified MOSFET is produced in a rugged gate version of Fairchild Semiconductor's advanced PowerTrench process. It has been optimized for power management applications for a wide range of gate drive voltages (2.5V-12V).

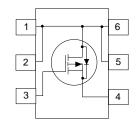
Applications

- Load switch
- Power management
- DC/DC converter

Features

- -1.5 A, -20 V. $R_{DS(ON)} = 0.145 \Omega$ @ $V_{GS} = -4.5 V$ $R_{DS(ON)} = 0.210 \Omega$ @ $V_{GS} = -2.5 V$
- Low gate charge
- High performance trench technology for extremely low Rosconn
- Compact industry standard SC70-6 surface mount package





SC70-6

Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parameter	Ratings		
V _{DSS}	Drain-Source Voltage		-20	V
V _{GSS}	Gate-Source Voltage		± 12	V
I _D	Drain Current - Continuous	(Note 1a)	-1.5	Α
	- Pulsed	Ī	-6	
P _D	Power Dissipation for Single Operation	(Note 1a)	0.75	W
		(Note 1b)	0.48	
T _J , T _{STG}	Operating and Storage Junction Temperat	-55 to +150	°C	

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1b)	260	°C/W
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Package Marking and Ordering Information

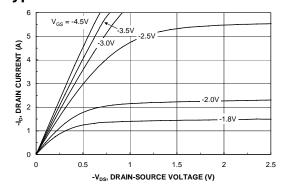
Device Marking	Device	Reel Size	Tape width	Quantity
.28	.28 FDG328P		8mm	3000 units

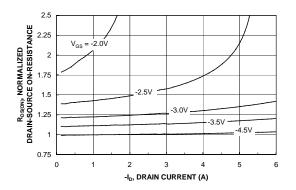
Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	racteristics		I	I	I	
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	-20			V
ΔBV _{DSS} ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = -250 μ A, Referenced to 25°C		- 9		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}$			-1	μΑ
I _{GSSF}	Gate-Body Leakage, Forward	$V_{GS} = 12 \text{ V}, \qquad V_{DS} = 0 \text{ V}$			100	nA
I _{GSSR}	Gate-Body Leakage, Reverse	$V_{GS} = -12 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Chai	racteristics (Note 2)					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-0.6		-1.5	>
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = -250 \mu\text{A}$, Referenced to 25°C		3	145	mV/°C
$R_{\text{DS(on)}}$	Static Drain–Source On–Resistance	lesistance $V_{GS} = -2.5 \text{ V}, I_{D} = -1.2 \text{ A}$ 169				
I _{D(on)}	On-State Drain Current	$V_{GS} = -4.5 \text{ V}, I_D = -1.5 \text{ A}, T_J=125^{\circ}\text{C}$ $V_{GS} = -4.5 \text{ V}, V_{DS} = -5 \text{ V}$	-3			Α
g FS	Forward Transconductance	$V_{DS} = -5 \text{ V}, \qquad I_{D} = -1.5 \text{ A}$		5		S
Dynami	c Characteristics					
C _{iss}	Input Capacitance	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V},$		337	7	pF
Coss	Output Capacitance	f = 1.0 MHz				pF
C _{rss}	Reverse Transfer Capacitance		51		pF	
Switchin	ng Characteristics (Note 2)					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = -10 \text{ V}, I_D = 1 \text{ A},$		9	18	ns
t _r	Turn-On Rise Time	$V_{GS} = -4.5 \text{ V}, R_{GEN} = 6 \Omega$	12		22	ns
$t_{d(off)}$	Turn-Off Delay Time			10	20	ns
t _f	Turn-Off Fall Time			5	10	ns
Q_g	Total Gate Charge	$V_{DS} = -10 \text{ V}, I_{D} = -1.5 \text{ A},$		3.7	6	nC
Q_{gs}	Gate-Source Charge	$V_{GS} = -4.5 \text{ V}$	0.7	,	nC	
Q_{gd}	Gate-Drain Charge			1.3	3	nC
Drain-S	ource Diode Characteristics	and Maximum Ratings				
Is	Maximum Continuous Drain-Sourc	•			-0.62	Α
V _{SD}	Drain–Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = -0.62 \text{ A (Note 2)}$		-0.7	-1.2	V

Notes:

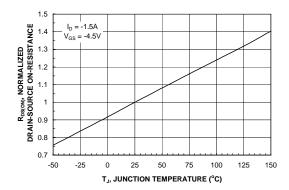
- 1. R_{0JA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{0JC} is guaranteed by design while R_{0CA} is determined by the user's board design.
 - a.) 170°/W when mounted on a 1 in² pad of 2 oz. copper.
 - b.) 260°/W when mounted on a minimum pad.
- 2. Pulse Test: Pulse Width < 300µs, Duty Cycle < 2.0%

Typical Characteristics





Characteristics



Current

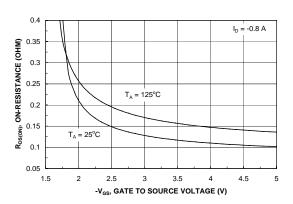


Figure 3. On-Resistance Variation withTemperature.

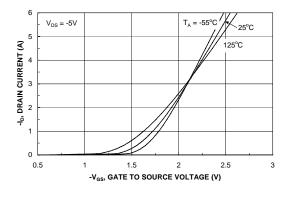


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

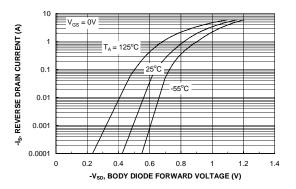
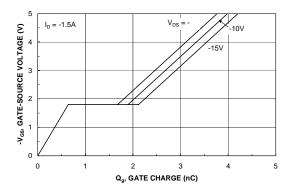


Figure 5. Transfer Characteristics.

Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics



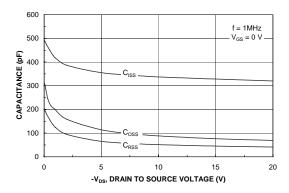
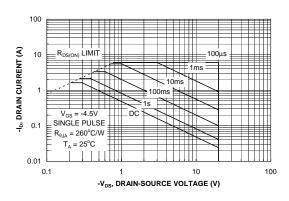


Figure 7. Gate Charge Characteristics.

Figure 8. Capacitance Characteristics.



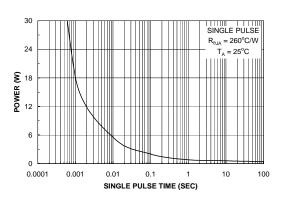


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

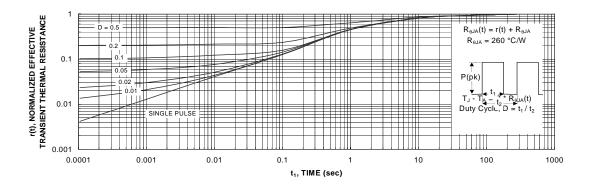


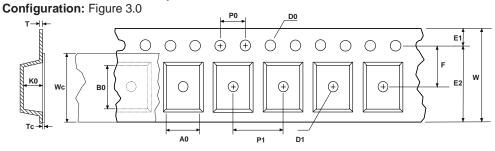
Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient themal response will change depending on the circuit board design.

SC70-6 Tape and Reel Data FAIRCHILD SEMICONDUCTOR TA SC70-6 Packaging Configuration: Figure 1.0 **Packaging Description:** Customized Label Packaging Description: SC7/0-6 parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate reason. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 3,000 units per 7" or 177cm diameter reel. The reels are dark blue in color and is made of polystyrene plastic (anti-static coated). Other option comes in 10,000 units per 13" or 330cm diameter reel. This and some other options are described in the Packaging Information table. Antistatic Cover Tape These full reels are individually barcode labeled and Iness tull rees are individually barcode labeled and placed inside a pizza box (illustrated in figure 1.0) made of recyclable corrugated brown paper with a Fairchild logo printing. One pizza box contains three reels maximum. And these pizza boxes are placed inside a barcode labeled shipping box which comes in different sizes depending on the number of parts shipped. F63TNR Static Dissipative Label **Embossed Carrier Tape** 15.75 • 21 SC70-6 Packaging Information Standard Packaging Option SC70-6 Unit Orientation Packaging type 10,000 Qty per Reel/Tube/Bag 3,000 13" Reel Size 7" Dia Box Dimension (mm) 184x187x47 343x343x64 Max qty per Box 9,000 30,000 343mm x 342mm x 64mm F63TNR Barcode Label Weight per unit (gm) 0.0055 0.0055 0.1140 Intermediate box for D87Z Option Weight per Reel (kg) 0.3960 F63TNR Label F63TNR Label sample 184mm x 187mm x 47mm Pizza Box for Standard Option D/C1: D9842 QTY1: D/C2: QTY2: SPEC REV (F63TNR)3 **SC70-6 Tape Leader and Trailer** Configuration: Figure 2.0 0 0 0 \bigcirc 0 0 \bigcirc 0 Carrier Tape Components Cover Tape Trailer Tape Leader Tape 300mm minimum or 500mm minimum or 75 empty pockets 125 empty pockets



SC70-6 Embossed Carrier Tape



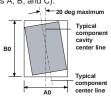


Dimensions are in millimeter														
Pkg type	Α0	В0	w	D0	D1	E1	E2	F	P1	P0	K0	Т	Wc	Тс
SC70-6 (8mm)	2.24 +/-0.10	2.34 +/-0.10	8.0 +/-0.3	1.55 +/-0.05	1.125 +/-0.125	1.75 +/-0.10	6.25 min	3.50 +/-0.05	4.0 +/-0.1	4.0 +/-0.1	1.20 +/-0.10	0.255 +/-0.150	5.2 +/-0.3	0.06 +/-0.02

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



Sketch A (Side or Front Sectional View)
Component Rotation



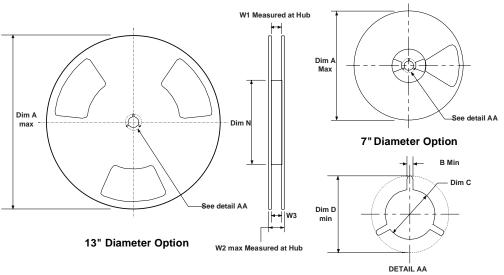
Sketch B (Top View)

Component Rotation



Sketch C (Top View)
Component lateral movement

SC70-6 Reel Configuration: Figure 4.0



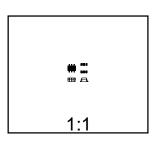
Dimensions are in inches and millimeters									
Tape Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2	Dim W3 (LSL-USL)
8mm	7" Dia	7.00 177.8	0.059 1.5	0.512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	2.165 55	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9
8mm	13" Dia	13.00 330	0.059 1.5	0.512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	4.00 100	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9

SC70-6 Package Dimensions



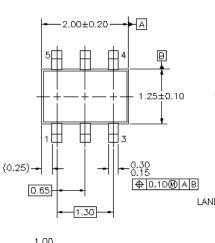
SC70-6 (FS PKG Code 76)

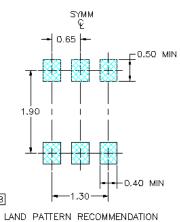


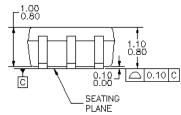


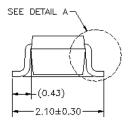
Scale 1:1 on letter size paper Dimensions shown below are in: inches [millimeters]

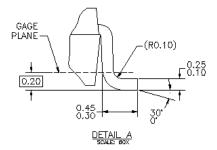
Part Weight per unit (gram): 0.0055











NOTES: UNLESS OTHERWISE SPECIFIED

- THIS PACKAGE CONFORMS TO EIAJ SC-8B, 1996. ALL DIMENSIONS ARE IN MILLIMETERS. DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH.

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Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
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